JTO 深	圳市晶腾 <del>)</del>	化电有限公	司 CS Co LTD			
Produc Mo APPRO CUSTOMER :	ct Specificatio odel NO. : JTO REVISIO OVAL FOR SPECI	on For LCD Mo TFT35312001 ON : 1 FICATIONS ONLY FICTAIONS AND APPROVED BY :	odule A SAMPLE			
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APPROVED BY	CHECKED BY	PREPARED BY				
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REV	COMMENT	PAGE	DATE
1	Initial Release	1-20	2014/01/06





GI	ENERAL SPECIFICATI	ON
	ITEM	CONTENTS
	Module Size	76.9(W)× 63.9(H)× 3.15(T) mm
	Display Format	320× 240 DOTS
	View Area	72.88 (W) × 55.36(H) mm
	Dot Size	-
	Dot Pitch	0.108mm * 0.108mm
	LCD Type	TFT
	View Angle	12 O'clock
	Controller IC	HX8238-D
	Duty Ratio	-
	Bias	-
	Backlight Driver type	External Power
	DC to DC circuit	Build-In
	Weight	



### MODEL NO.

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# ELECTRO-OPTICAL CHARACTERISTICS (Ta=25°C)

#### ELECTRICAL SPECIFICATION

ltom	Symbol	, N	Unit		
llem	Syllibol	Min.	Тур	Max.	- Onit
TFT gate on voltage	V <sub>GH</sub>	2 <del>7</del> 5	+15	<del></del>	V
TFT gate off voltage	V <sub>GL</sub>	1.75	-10	3. <del></del> 1	V
TFT common electrode	V <sub>comH</sub>	2.5	(3.6)	4.5	v
voltage	V <sub>comL</sub>	-3	(-2.4)	0	

Note: (1) Vcom must be adjusted to optimize display quality: cross talk, contrast ratio and etc.

(2) VGH is TFT gate operating voltage

(3) VGL is TFT gate operating voltage

(4) Environmental condition: 25±5°C

## BACKLIGHT

PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I	-	20	-	mA		
Supply Voltage	V	18	-	-	V	-	
Luminous Intensity IV	-			350	Cd/m <sup>2</sup>		
Uniformity	-	80		-	%		
Chromotiaty Coordinate	Х	0.28		0.31	nm		
Chromaticty Coordinate	Y	0.29		0.32	nm		
Color					White		



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### LCD OPTICALCHARACTERISTICS/COLOROFCIECOORDINATE

Itom		Oumhal	Conditions	Spe	ecificati	ons	Linit	Mata
item		Symbol	Conditions	Min.	Тур.	Max.	Unit	Note
Transmittance	e	Т%	9		7.4		%	
Contrast Ratio		CR	0	200	300			All left side data
		TR			15	30	ms	are based on
Response ni	ne	TF			35	50	ms	condition T6
	Dod	X <sub>B</sub>		0.609	0.639	0.669		NTSC: 60%
	neu	YR	Viewing normal angle	0.314	0.344	0.374	2	LC:5091
	Croop X <sub>G</sub>	viewing normal angle	0.264	0.294	0.324		Light : C light	
Chromoticity	Green	YG	$\partial \chi = \partial \gamma = 0^{-1}$	0.557	0.587	0.617		(Machine:BM5A)
Chromaticity	Dhua	XB	8	0.102	0.132	0.162	8	Normal Polarizer
	Blue	Blue Y <sub>B</sub>	1	0.106	0.136	0.166	8	Without DBEF
	White	Xw		0.282	0.312	0.342		"Simulation
	vvnite	Yw		0.319	0.349	0.379		Data
	Llor	θ <b>χ</b> +		musmusm	45			Reference
Viewing	Hor.	θχ.	Center		45		dog	Only"
Angle	le Vor θ <sub>Y+</sub> CR≥1	CR≥10		15		ueg.		
	ver.	θγ.			35			

\*Note (1) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63

L 0: Luminance of gray level 0

CR = CR (10)

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (5).

\*Note (2) Definition of Response Time (TR, TF):







\*Note (4) Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.





PIN	SYMBOL	FUNCTIONS					
1	LED_CATHOD	LED Light Power Supply .0V					
2	LED_CATHOD	LED Light Power Supply .0V					
3	LED_ANODE	LED Light Power Supply .19.2V					
4	LED_ANODE	LED Light Power Supply .19.2V					
5	Y1	Top electrode					
6	X1	Right electrode					
7	NC	Not use					
8	REST	This signal will reset the device and must be applied to properly initialize the chip					
9	SPENA	Chip select input PIN of serial interface					
10	SPCLK	Clock PIN of serial interface					
11	SPAD	Data input pin in serial interface					
12~35	D0~D23	Data Bit0 ~Data Bit23					
36	HSYNC	lorizontal sync signal in RGB I/F					
37	VSYNC	Vertical sync signal in RGB I/F					
38	DOTCLK	Pixel clock signal in RGB I/F					
39	NC	Not use					
40	NC	Not use					
41	VDD	Power Supply For Logic					
42	VDD	Power Supply For Logic					
43	Y2	Bottom electrode					
44	X2	Left electrode					
45	NC	Not use					
46	NC	Not use					
47	NC	Not use					
48	IF2	Control the input data format					
49	IF1	Control the input data format					
50	IF0	Control the input data format					
51	NC	Not use					
52	DEN	Data enable signal in RGB I/F					
53	GND	This is a 0V terminal connected to the system GND.					
54	GND	This is a 0V terminal connected to the system GND.					



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Note: External clock source must be provided to DOTCLK pin of HX8238-A. The driver will not operate if absent of the clocking signal.

Table 13. 1 Pixel Timing



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Figure 13. 3 Data Transaction Timing in Parallel RGB (24 bit) Interface (DE Mode)

Characteristics		Symbol	Min.		Тур.		Ma	ax.	Unit	
		Symbol	24 bit	8 bit	24 bit	8 bit	24 bit	8 bit	Unit	
DOTCLK Frequer	icy	DOTCLK	0	•	6.5	19.5	10	30	MHz	
DOTCLK Period	-61	- tDOTCLK	100	33.3	154	51.3	-	-	ns	
Horizontal Freque	ncy (Line)	fH( ( ) )		er j	14	.9	22	.35	KHz	
Vertical Frequence	y (Refresh)	NTV V	-		6	0	9	0	Hz	
Horizontal Back P	orch	< there	- 14 I.		68	204	-	•	tDOTCLK	
Horizontal Front F	orch	THEP			20	60	· · ·		<b>tDOTCLK</b>	
Horizontal Data S	tart Point	tHBP			68	204	-	•	tDOTCLK	
Horizontal Blankin	g Period	tHBP + tHFP			88	264	-		<b>tDOTCLK</b>	
Horizontal Display	Area	HDISP	- 84 I.	, se .	320	960	÷.,		<b>tDOTCLK</b>	
Horizontal Cycle		Hcycle	) 34 ()		408	1224	450	1350	tDOTCLK	
Vertical Back Por	ch	tVBP			18				Lines	
Vertical Front Por	ch	tVFP	-		4			. I.	Lines	
Vertical Data Star	t Point	tVBP			18				Lines	
Vertical Blanking	Period	tVBP + tVFP	-		2	2		e - 1	Lines	
Vartical Diaplay	NTSC		5		24	10		Ĩ		
Vertical Display	DAL	VDISP		1	280(PA	LM=0)	1		Lines	
Alea	PAL				288(PA	LM=1)	1			
	NTSC	1.0000000000	-		26	2			100000000	
Vertical Cycle	PAL	Vcycle			212		350		Lines	

Table 13. 2 Data Transaction Timing in Normal Operating Mode



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# DC CHARACTERISTICS

#### **DC Characteristics**

(Unless otherwise specified, Voltage Referenced to Vss, Vodio = 2.2V, Ta = 25℃)

Sumbol	Deremotor	Test condition	6	Spec.		Unit
Symbol	Parameter	Test condition	Min	Тур	Max	onit
VDD	System power supply pins of the logic block	Recommend Operating Voltage Possible Operating Voltage	1.8	-	2.50	۷
VDDIO	Power supply pin of IO pins	Recommend Operating Voltage Possible Operating Voltage	1.8	2	3.6	v
Vci	Booster Reference Supply Voltage Range	Recommend Operating Voltage Possible Operating Voltage	2.5 or VDDIO	6	3.6	v
Isleep	Sleep mode current	-	A ()	∧ 50 <sup>-</sup>		μA
lap	Operating mode current	VCI=3.3V	12.4	/10	12	mA
Vcim	Negative V <sub>cl</sub> Output Voltage	No panel loading	STACK	-	- VCI+0.7	V
V <sub>CIX2</sub>	V <sub>CIX2</sub> primary booster efficiency <sup>(1)</sup>	No panel loading, ITO for V <sub>CIX2</sub> , V <sub>CI</sub> and V <sub>CHS</sub> = 10 Ohm	83	90	-	%
		No panel loading; 4x booster; ITO for Cyp, Cyn, Vcix2, Vci and Vciis = 10 Ohm	84	89.5	170	%
V <sub>GH</sub>	Gate driver High Output Voltage Booster efficiency <sup>(2)</sup>	No panel loading; 5x booster; ITO for C <sub>YP</sub> , C <sub>YN</sub> , V <sub>CK2</sub> , V <sub>CI</sub> and V <sub>CHS</sub> = 10 Ohm	80	88.5		%
		No panel loading; 6x booster; ITO for Cyp, Cyn, Vcix2, Vci and Vcits = 10 Ohm	72	80	( <b>1</b> 2)	%
VGL	Gate driver Low Output Voltage	· (V) R(	/- V <sub>GH</sub>	i centi	-5.1	V
Vcomh	VCOM High Output Voltage	· @ ( 1	-	. 93	5.56	V
VCOML	VCOM Low Output Voltage	$\cdot$	Vcim+0.2		-	V
VCOMA	VCOM Amplitude		-		6	V
VLCD63	VLCD63 Output Voltage	0 52	-		5.59	V
	Max. Source Voltage Variation		-2		2	%
V <sub>OH1</sub>	Logic High Output Voltage	I out = -100µA	0.9*V <sub>DDIO</sub>	8 300	VDD	V
Vvd	Source Output Voltage Deviation			±20		mV
Vos	Source Output Voltage Offset	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~		1 620	±30	mV
Voli	Logic Low Output Voltage	l out = 100µA	0	] 👘 ]	0.1*VDDЮ	V
V <sub>IH1</sub>	Logic High Input voltage	· //	0.8*Vppio		V <sub>DDIO</sub>	V
VIL1	Logic Low Input voltage		0		0.2*VDDЮ	V
I <sub>OH</sub>	Logic High Output Current Source	Vout = VDD - 0.4V	50	8 x=0 8	0	μA
lo <sub>L</sub>	Logic Low Output Current Drain	V out = 0.4V	1		-50	μΑ
loz	Logic Output Tri-state Current Drain Source	-	-1	•	1	μA
INTH C	Logic Input Current	<b>7</b> .3	-1	1.00	1	μA
CIN	Logic Pins Input Capacitance	-9		5	7.5	pF
RSON	Source drivers output resistance	-	-	1	1993	kΩ
RGON	Gate drivers output resistance	÷9		500	( est	Ω
RCON	VCOM output resistance	•/	-	200	1.00	Ω

Note : (1) VCIX2 efficiency = VCIX2 / (2 x VCI) x 100% (2) VGH efficiency = VGH / (VCI x n) x 100% (where n = booster factor)

Table 12. 1 DC Characteristics



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	No	Test Item	Content of Test	Test
				Condition
	1	High Temperature	Endurance test of high temperature for a long	60±2℃
		Storage	time.	48H
	2	Low Temperature	Endurance test of low temperature for a long	-20±2℃
		Storage	time.	48H
	3	High Temperature	Endurance test of electrical stress (Voltage &	60±2℃
est		Operation	Current) and the thermal stress to the	48H
int T			element.	
nme	4	High Temperature	Endurance Test of high temperature and high	60±2℃
viro		/Humidity	humidity for a long time.	$60\pm2\%$ RH
En		Storage		48H
	5	Thermal shock	Endurance test of low and high temperature	-20±2°C/7
			cycles.(air to air)	$\pm 2$ °C
			$-20\pm2^{\circ}C \iff 60\pm2^{\circ}C$	10 cycle
			$(60\min)  \longleftrightarrow  (60\min)$	
			1 cycle	

Note: 1) When making the low temperature test, not to dewy.

2) Driving condition for operation test.

Power Supply Voltage for Logic System (VDD) =2.8V

Failure Judgment Criterion

After the above mentioned test.

(For Environmental Test, after 2 hours in room temperature.)

There should not be conspicuous failure of display quality and appearance.

2) Contrast ratio should be 50% of the initial contrast ratio.

3) There should not have any abnormality of functions.



D.	ltem	Criterion				
1	Short or open circuit		Not allow			
	LC leakage					
	Flickering					
	No display					
	Wrong viewing direction					
	Wrong Back-light					
2	Contrast defect		Refer to approval sa	mple		
	Background color deviation					
			Point Size	Acceptable Qty.		
	Point defect, Black spot_dust		φ <u>&lt;</u> 0.10	Disregard		
	(including Polarizer)	<b>O</b> ĴŸ	0.10<∳≤0.20	3		
3	φ = (X+Y)/2	₩X	0.20<∳≦0.25	2		
		8650	0.25<∳≦0.30	1		
	A		φ>0.30	0		
			Unit : mm			
			Line	Acceptable Qty.		
	Line defect	J	0.015≥W	Disregard		
		C → w	3.0≥L 0.03≥W	2		
4	Constal	$\leftrightarrow$	2.02L 0.052W	1		
	Scratch	L	0.05 <w< td=""><td>Applied as point defect</td></w<>	Applied as point defect		
			Unit : mm			
5	Rainbow	Not more than t	wo color changes acro	oss the viewing area.		



No.	Item	Criterion
6	Segment pattern W = Segment width ∳ = (X+Y)/2	(1) Pin hole $\phi < \text{ is acceptable.}$ $\gamma \rightarrow \gamma \gamma$ $\gamma \rightarrow \gamma \gamma$ $\phi \le 1/4W$ Disregard $1/4W < \phi \le 1/2W$ 0 Unit : mm
7	Back-light	<ul><li>(1) The color of backlight should correspond its specification.</li><li>(2) Not allow flickering</li></ul>
8	Soldering	<ul> <li>(1) Not allow heavy dirty and solder ball on PCB. (The size of dirty refer to point and dust defect)</li> <li>(2) Over 50% of lead should be soldered on Land.</li> </ul>
9	Wire	<ul> <li>(1) Copper wire should not be rusted</li> <li>(2) Not allow crack on copper wire connection.</li> <li>(3) Not allow reversing the position of the flat cable.</li> <li>(4) Not allow exposed copper wire inside the flat cable</li> </ul>
10	РСВ	<ul><li>(1) Not allow screw rust or damage.</li><li>(2) Not allow missing or wrong putting of component.</li></ul>
11	Total No. of Acceptable Defect	A Zone Maximum 2 minor non-conformities per one unit. Defect distance: each point to be separated over 10mm B. Zone It is acceptable when it is no trouble for quality and assembly in customer's end product.



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## Precaution for use of LCD module

- 11.1 Handling Precautions
  - 1) The display panel is made of glass. Do not subject it to a mechanical shock•by dropping it from a high place, etc.
  - 2) If the display panel is damaged and the liquid crystal substance inside it leaks out ,be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
  - 3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
  - 4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
  - 5) If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
    - --Isopropyl alcohol
    - --Ethyl alcohol
    - Solvents other than those mentioned above may damage the polarizer.
    - Especially, do not use the following:
    - --Water
    - --Ketone
    - --Aromatic solvents
  - 6) Do not attempt to disassemble or process the LCD module.

  - When mounting the LCD module make sure that it is free of twisting, warping, and distortion. Distortion has great influence upon display quality. Also keep the stiffness enough regarding the outer case.
  - 2) Please handle the LCD module by its side.
  - 3) NC terminal should be open. Do not connect anything.
  - 4) If the logic circuit power is OFF, do not apply the input signals.
  - 5) To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
    - Be sure to ground the body when handling the LCD module.
    - ·Tools required for assembly, such as soldering irons, must be properly grounded.
      - •To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
      - •The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
  - 6) Be careful when treating the glass panel because it has very sharpened edge.
  - • 3• Storage Precautions



5) Precaution for disposal of LCD module. When disposal of LCD module, ask specialization company of industrial waste which is permitted by the government. When burn up LCD module, obey the law of environmental hygienics. wash it off well with soap and water.